

Cookson Group Plaskon® SMT-B-1 LAS (146.408) Epoxy Molding Compound for PBGAs (discontinued **)

Category : Polymer , Thermoset , Epoxy , Epoxy Molding Compound

Material Notes:

Test specimens were transfer molded and post cured 4 hours at 175°C. An epoxy molding compound optimized specifically for grid arrays (BGA/LGA) requiring low alpha particle count. It is formulated with a unique resin system which minimizes warpage and enables trouble-free molding onto laminated substrates. Minimal warpage (after post bake and solder treatment); Outstanding high temperature flexural strength; Low stress; Excellent moldability (low viscosity); Low alpha particle count

Order this product through the following link:

http://www.lookpolymers.com/polymer_Cookson-Group-Plaskon-SMT-B-1-LAS-146408-Epoxy-Molding-Compound-for-PBGAs-nbspdiscontinued-.php

| Physical Properties | Metric | English | Comments |
|---------------------|---------------------------------|---------------------------------|-----------------------------|
| Density | 1.88 g/cc | 0.0679 lb/in ³ | |
| Viscosity | 45000 cP @Temperature 175 °C | 45000 cP @Temperature 347 °F | Automatic orifice Viscosity |
| Spiral Flow | 140 cm | 55.1 in | 175°C/1000 psi |

| Mechanical Properties | Metric | English | Comments |
|-----------------------|----------|-----------|----------|
| Hardness, Shore D | 75 | 75 | |
| Flexural Strength | 103 MPa | 14900 psi | |
| Flexural Modulus | 14.0 GPa | 2030 ksi | |

| Thermal Properties | Metric | English | Comments |
|---------------------------------|--------------------------------------|--|----------|
| CTE, linear | 16.0 µm/m-°C @Temperature 20.0 °C | 8.89 µin/in-°F @Temperature 68.0 °F | |
| CTE, linear, Transverse to Flow | 68.0 µm/m-°C @Temperature 20.0 °C | 37.8 µin/in-°F @Temperature 68.0 °F | |
| Thermal Conductivity | 0.700 W/m-K | 4.86 BTU-in/hr-ft ² -°F | |
| Glass Transition Temp, Tg | 220 °C | 428 °F | |
| Flammability, UL94 | V-0 @Thickness 3.20 mm | V-0 @Thickness 0.126 in | |
| | V-0 @Thickness 3.20 mm | V-0 @Thickness 0.126 in | |

| Thermal Properties | Metric | English | Comments |
|------------------------|--------------------|--------------------|---------------------|
| Electrical Properties | Metric | English | Comments |
| Electrical Resistivity | >= 1.00e+15 ohm-cm | >= 1.00e+15 ohm-cm | |
| Dielectric Constant | 3.7 | 3.7 | |
| | @Frequency 1000 Hz | @Frequency 1000 Hz | |
| Dielectric Strength | 16.0 kV/mm | 406 kV/in | |
| Dissipation Factor | 0.0021 | 0.0021 | |
| | @Frequency 1000 Hz | @Frequency 1000 Hz | |
| Processing Properties | Metric | English | Comments |
| Processing Temperature | 170 - 185 °C | 338 - 365 °F | Molding temperature |

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